

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Yaojian Lin</td> <td>06/13/2013</td> </tr> <tr> <td>Kang Chen</td> <td>06/13/2013</td> </tr> <tr> <td>Yu Gu</td> <td>06/13/2013</td> </tr> <tr> <td>Pandi Chelvam Marimuthu</td> <td>06/13/2013</td> </tr> </tbody> </table>		Name	Execution Date	Yaojian Lin	06/13/2013	Kang Chen	06/13/2013	Yu Gu	06/13/2013	Pandi Chelvam Marimuthu	06/13/2013		
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RECEIVING PARTY DATA													
<table border="1"> <tr> <td>Name:</td> <td>STATS ChipPAC, Ltd.</td> </tr> <tr> <td>Street Address:</td> <td>10 Ang Mo Kio Street 65</td> </tr> <tr> <td>Internal Address:</td> <td>#05-17/20 Techpoint</td> </tr> <tr> <td>City:</td> <td>Singapore</td> </tr> <tr> <td>State/Country:</td> <td>SINGAPORE</td> </tr> <tr> <td>Postal Code:</td> <td>569059</td> </tr> </table>		Name:	STATS ChipPAC, Ltd.	Street Address:	10 Ang Mo Kio Street 65	Internal Address:	#05-17/20 Techpoint	City:	Singapore	State/Country:	SINGAPORE	Postal Code:	569059
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CORRESPONDENCE DATA													
<p>Fax Number: 4804999456  <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 480-499-9400        Email: main@plgaz.com        Correspondent Name: PATENT LAW GROUP: Atkins &amp; Associates        Address Line 1: 605 W. Knox Road        Address Line 2: Suite 104        Address Line 4: Tempe, ARIZONA 85284</p>													
ATTORNEY DOCKET NUMBER:	2515.0429 CIP												
NAME OF SUBMITTER:	Robert D. Atkins												

OP \$40.00 13917982

Signature:	/Robert D. Atkins/
Date:	06/14/2013
Total Attachments: 4 source=ASSIGNMENTS#page1.tif source=ASSIGNMENTS#page2.tif source=ASSIGNMENTS#page3.tif source=ASSIGNMENTS#page4.tif	

# ASSIGNMENT AND AGREEMENT

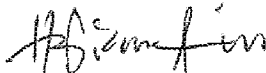
For good and valuable consideration, the receipt of which is hereby acknowledged, I, YAOJIAN LIN of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR METHOD AND DEVICE OF FORMING A FAN-OUT DEVICE WITH PWB VERTICAL INTERCONNECT UNITS, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 2515.0429 CIP and in U.S. Provisional Application No. 61/808,601, filed April 4, 2013, together with the entire right, title and interest in and to the applications, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above-identified invention(s). I hereby also sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the above-identified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

I hereby authorize and request the government authority in the United States to issue patent(s) upon the aforesaid application, continuation, division, reissue, reexamination, extension, renewal, or substitute, to STATS ChipPAC, for the sole use and behalf of STATS ChipPAC, its successors, assigns, and legal representatives, to the full end of the term for which the patent(s) may be granted, the same as they would have been held and enjoyed by me had this assignment not been made. I authorize and request the equivalent authorities in countries foreign to the United States to issue the patents of their respective countries to and in the name of STATS ChipPAC in the same manner.

I agree that, when requested, I will, without charge to STATS ChipPAC, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the invention(s) in any and all countries and for vesting title thereto in STATS ChipPAC, its successors, assigns, and legal representatives or nominees.

I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.



Signature for YAOJIAN LIN

Witnessed on this date:

13/6/2013.

Signature of Witness:



Printed Name of Witness:

ZHAI CHENGXIN

Address of Witness:

2, Woodlands Sector 1, #01-20,  
Woodlands Spectrum 1, Singapore 768442.

## ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, KANG CHEN of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR METHOD AND DEVICE OF FORMING A FAN-OUT DEVICE WITH PWB VERTICAL INTERCONNECT UNITS, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 2515.0429 CIP and in U.S. Provisional Application No. 61/808,601, filed April 4, 2013, together with the entire right, title and interest in and to the applications, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

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*chen kang*

Signature for KANG CHEN

Witnessed on this date:

13/6/2013

Signature of Witness:

*Zhou Chengxin*

Printed Name of Witness:

ZHOU CHENGXIN

Address of Witness:

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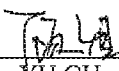
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\_\_\_\_\_  
Signature for YU GU

Witnessed on this date: 13/6/2013

Signature of Witness: 

Printed Name of Witness: 2HOU CHENGXIN

Address of Witness: 2, Woodlands Sector 1, #01-20  
Woodlands Spectrum 1, Singapore 768442.

## ASSIGNMENT AND AGREEMENT

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\_\_\_\_\_  
Signature for PANDI CHELVAM MARIMUTHU

Witnessed on this date: 13/6/2013  
Signature of Witness:   
Printed Name of Witness: ZHOU CHENGXIN  
Address of Witness: 2, Woodlands Sector 1, #01-20  
Woodlands Spectrum 1, Singapore 768442.